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Otsuka et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/110, 182; 257/678, 690; 361/713, 361/679.01, 728, 736, 775, 760, 761, 820; 324/754, 755, 756; 174/250, 253; 438/64, 65
See application file for complete search history.

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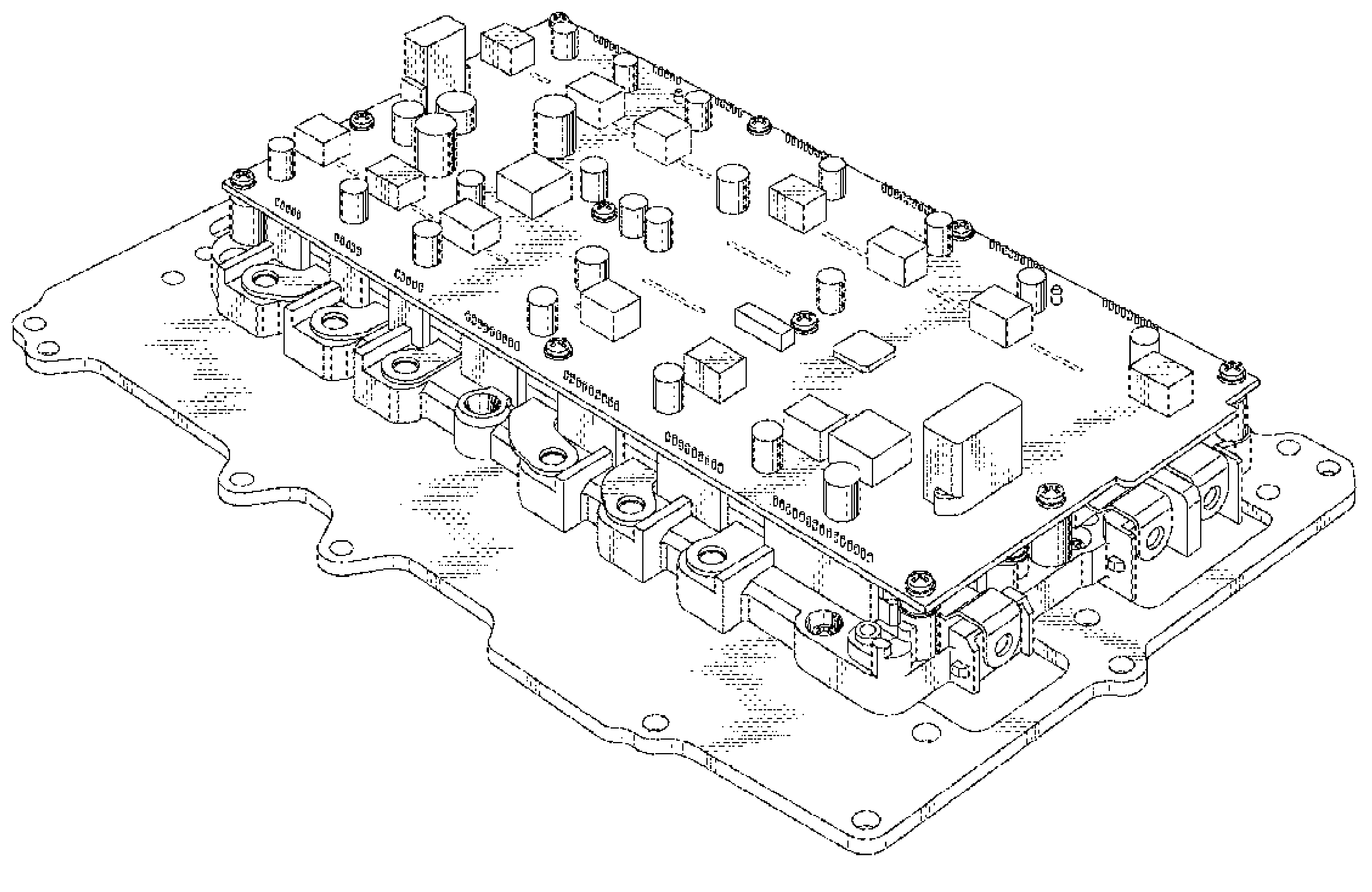
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a semiconductor device showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a right side view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a partially enlarged view thereof taken along lines VII-VII in FIG. **2**;
FIG. **8** is a partially enlarged view thereof taken along lines VIII-VIII in FIG. **4**;
FIG. **9** is a partially enlarged view thereof taken along lines IX-IX in FIG. **5**;
FIG. **10** is a front perspective view thereof; and,
FIG. **11** is a rear perspective view thereof.

1 Claim, 8 Drawing Sheets



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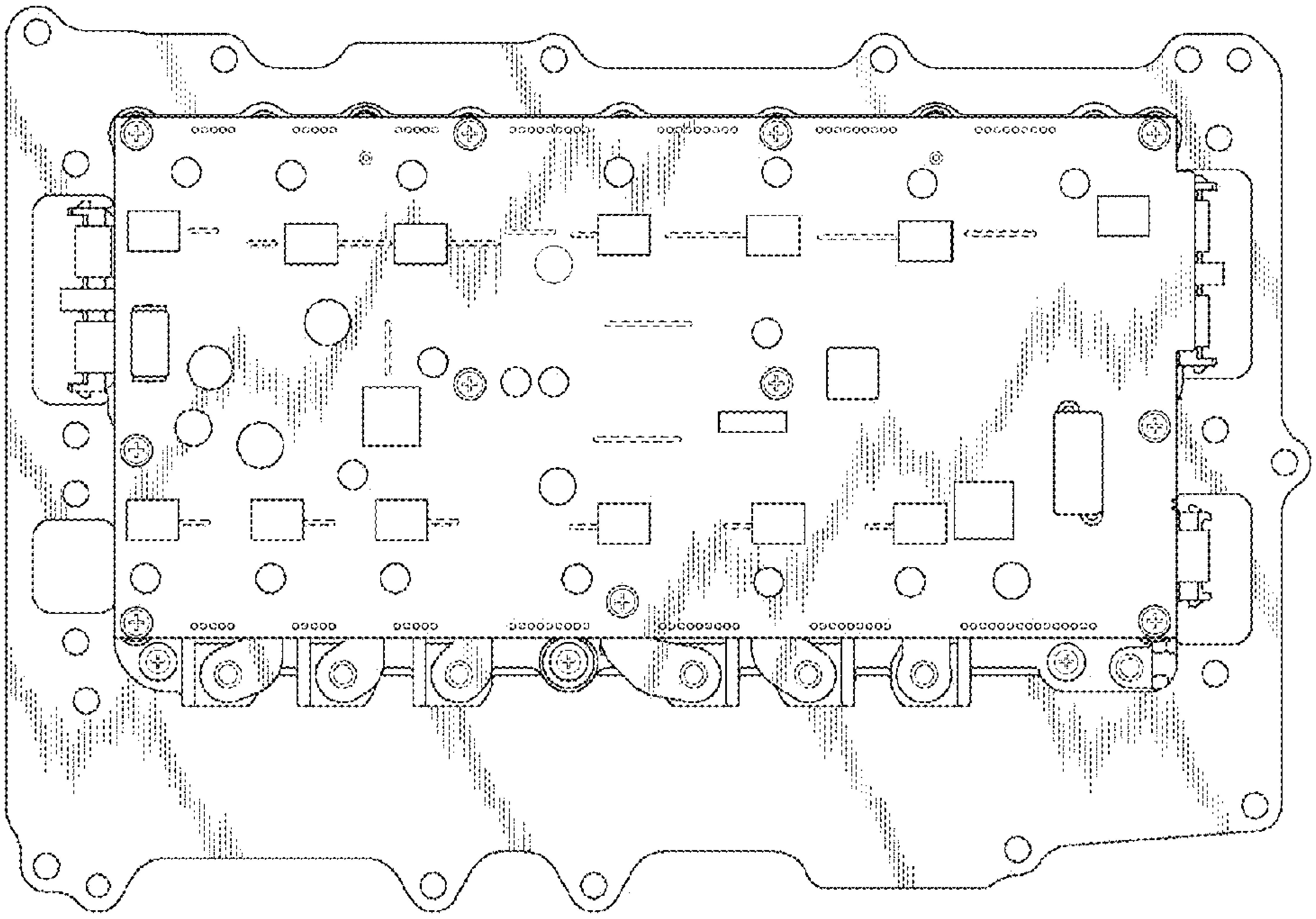

FIG.1

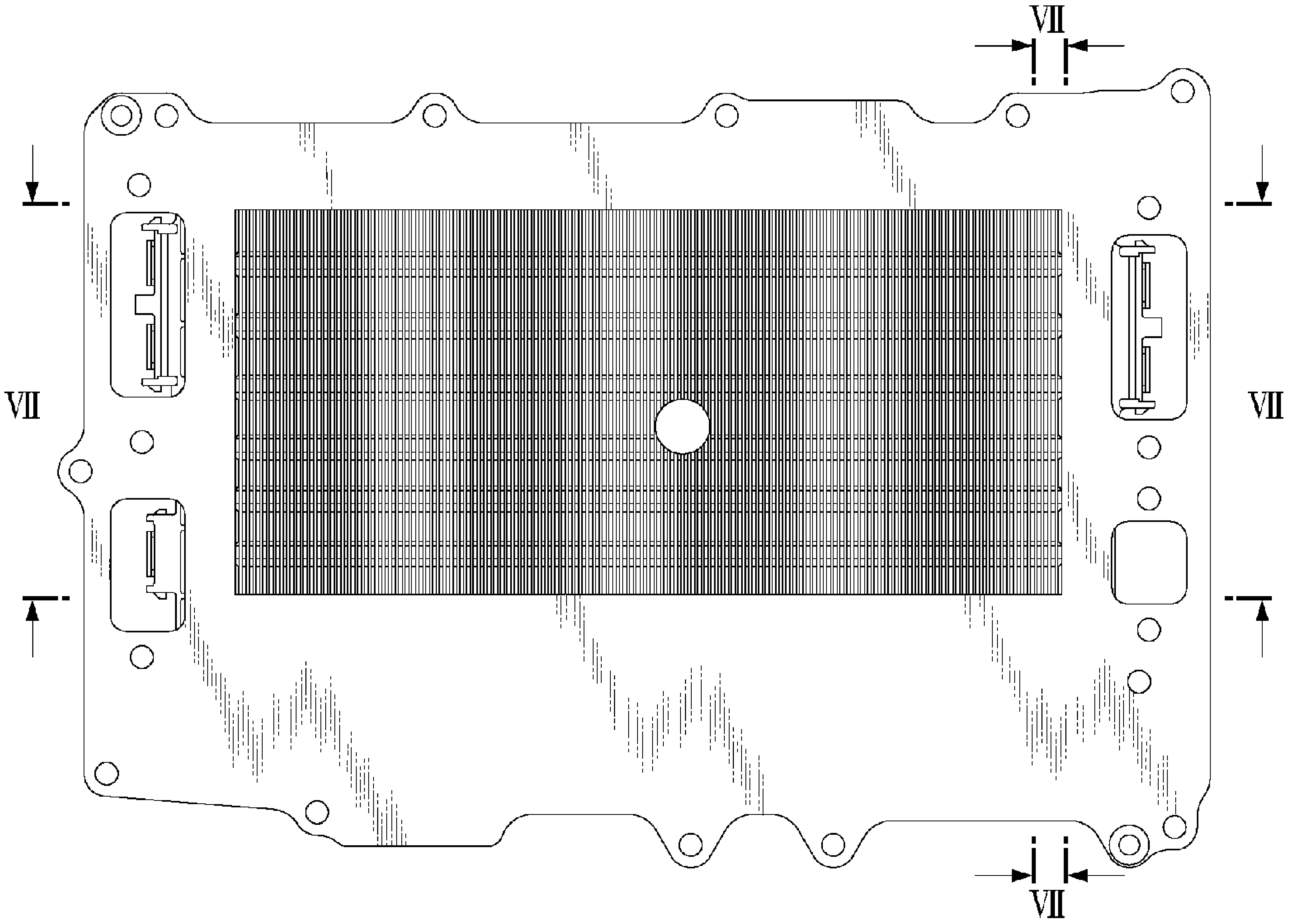

FIG.2

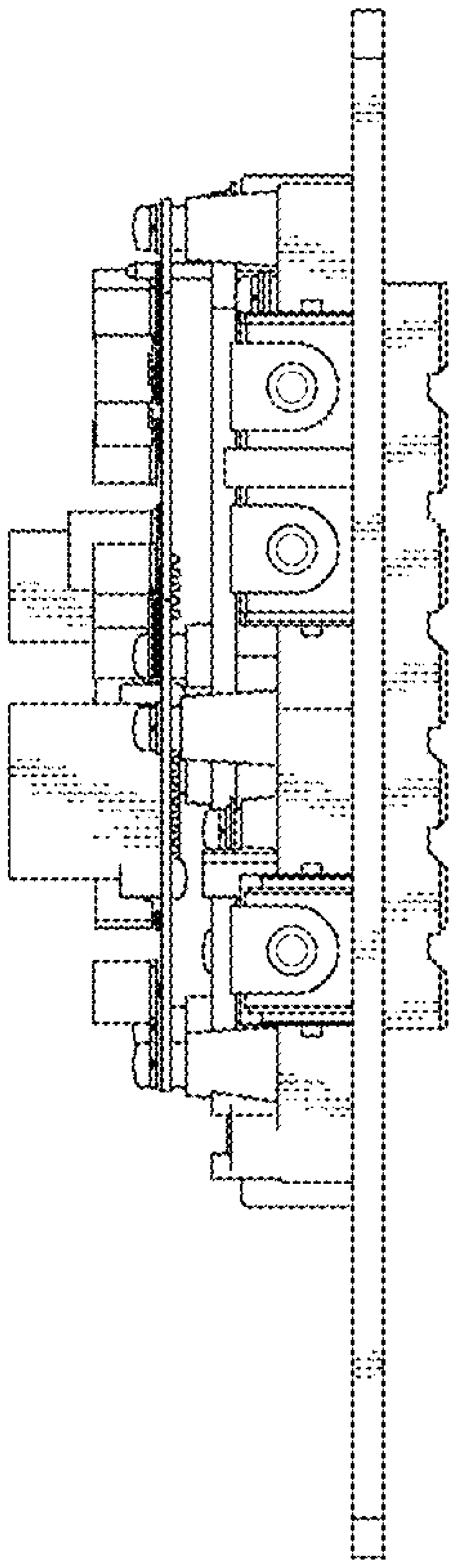

FIG.3

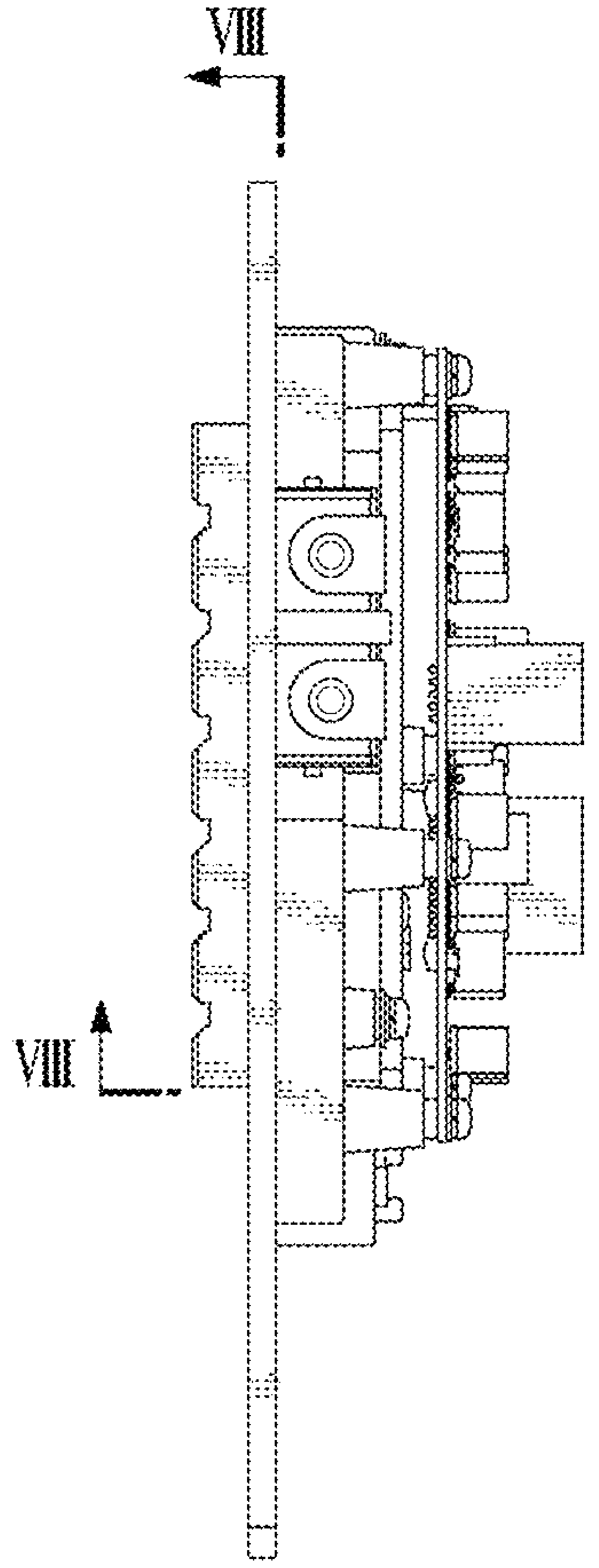

FIG.4

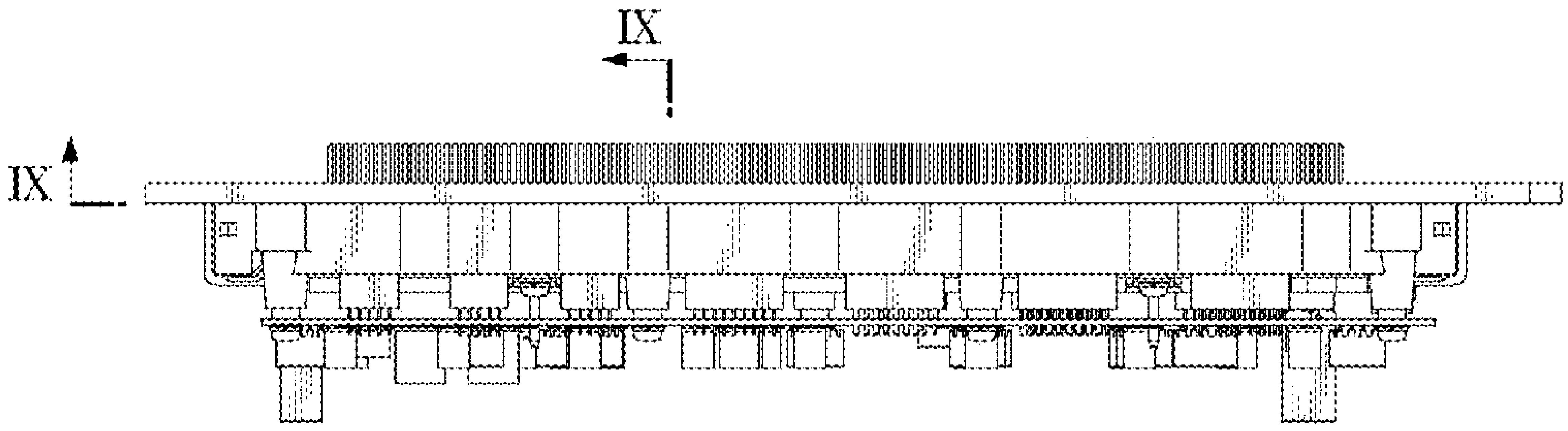

FIG.5

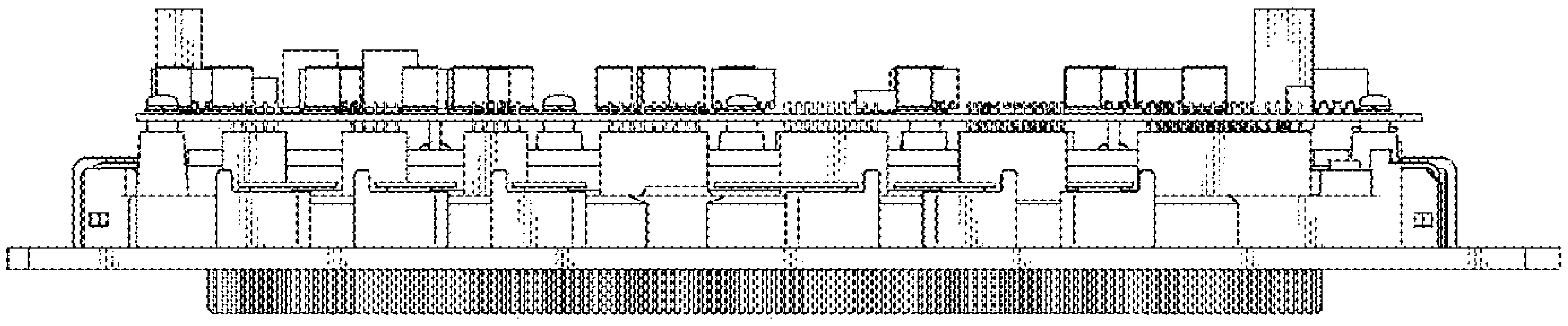

FIG.6

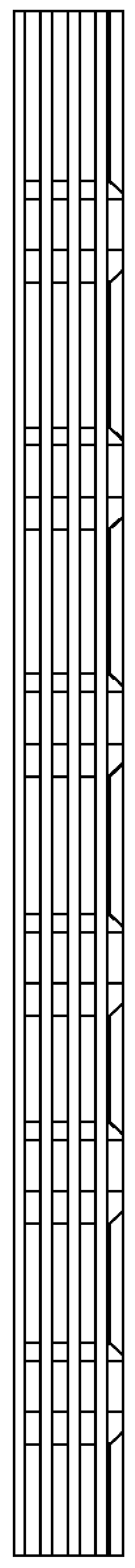

FIG.7

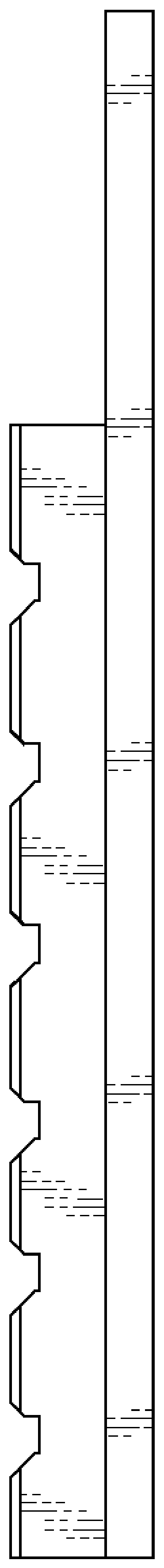

FIG.8

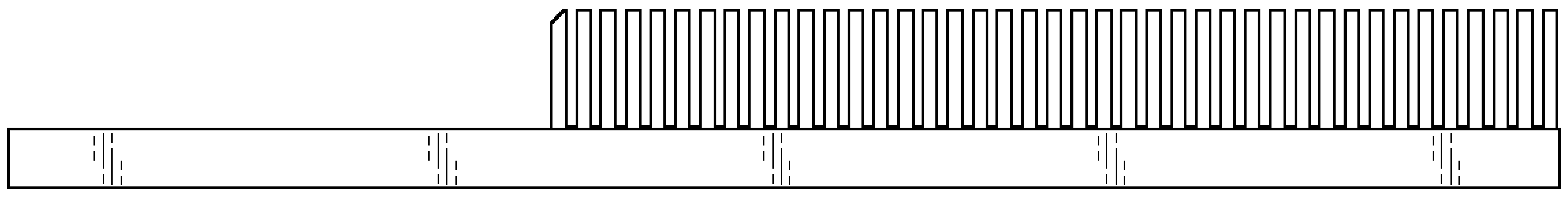

FIG.9

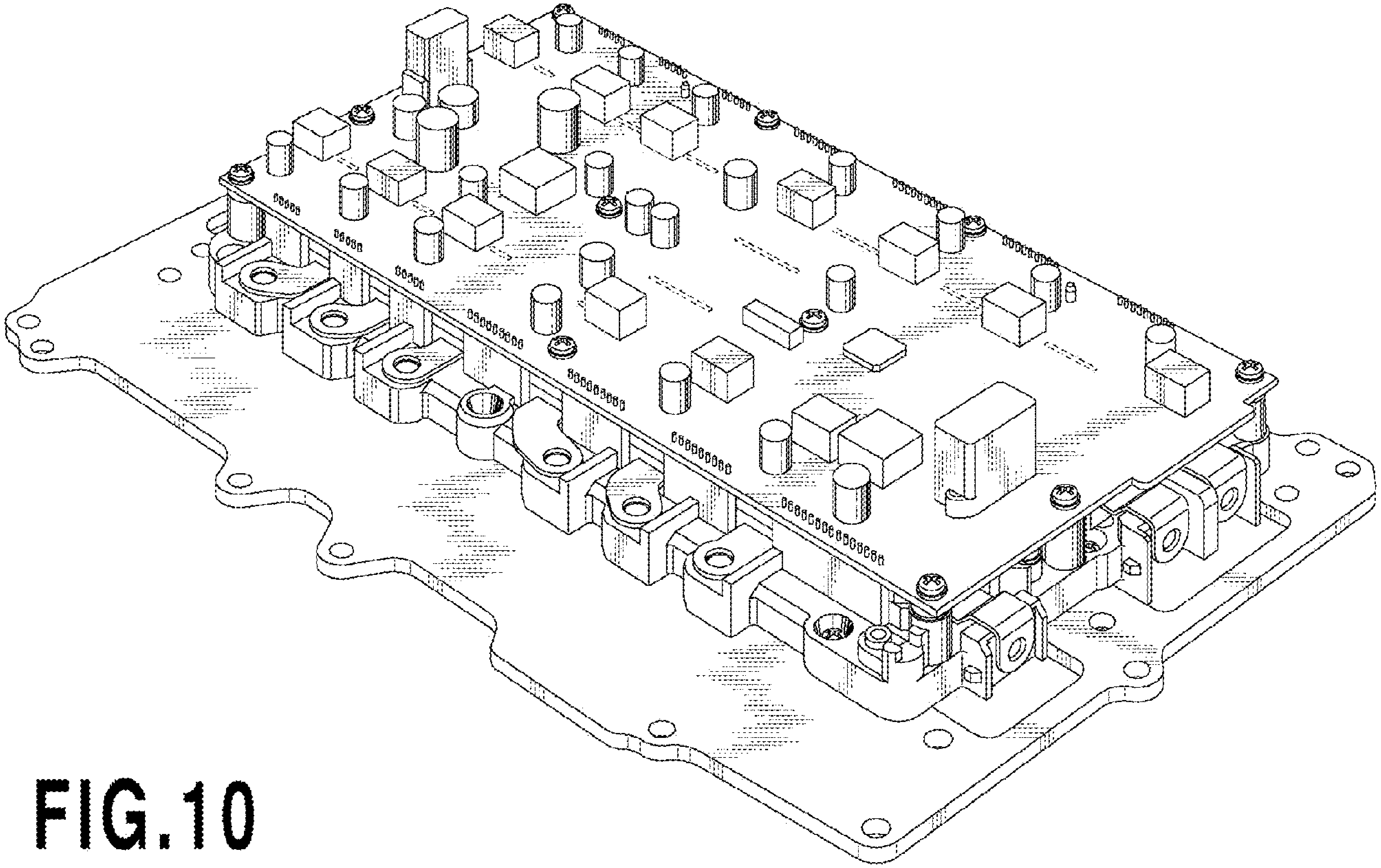

FIG. 10

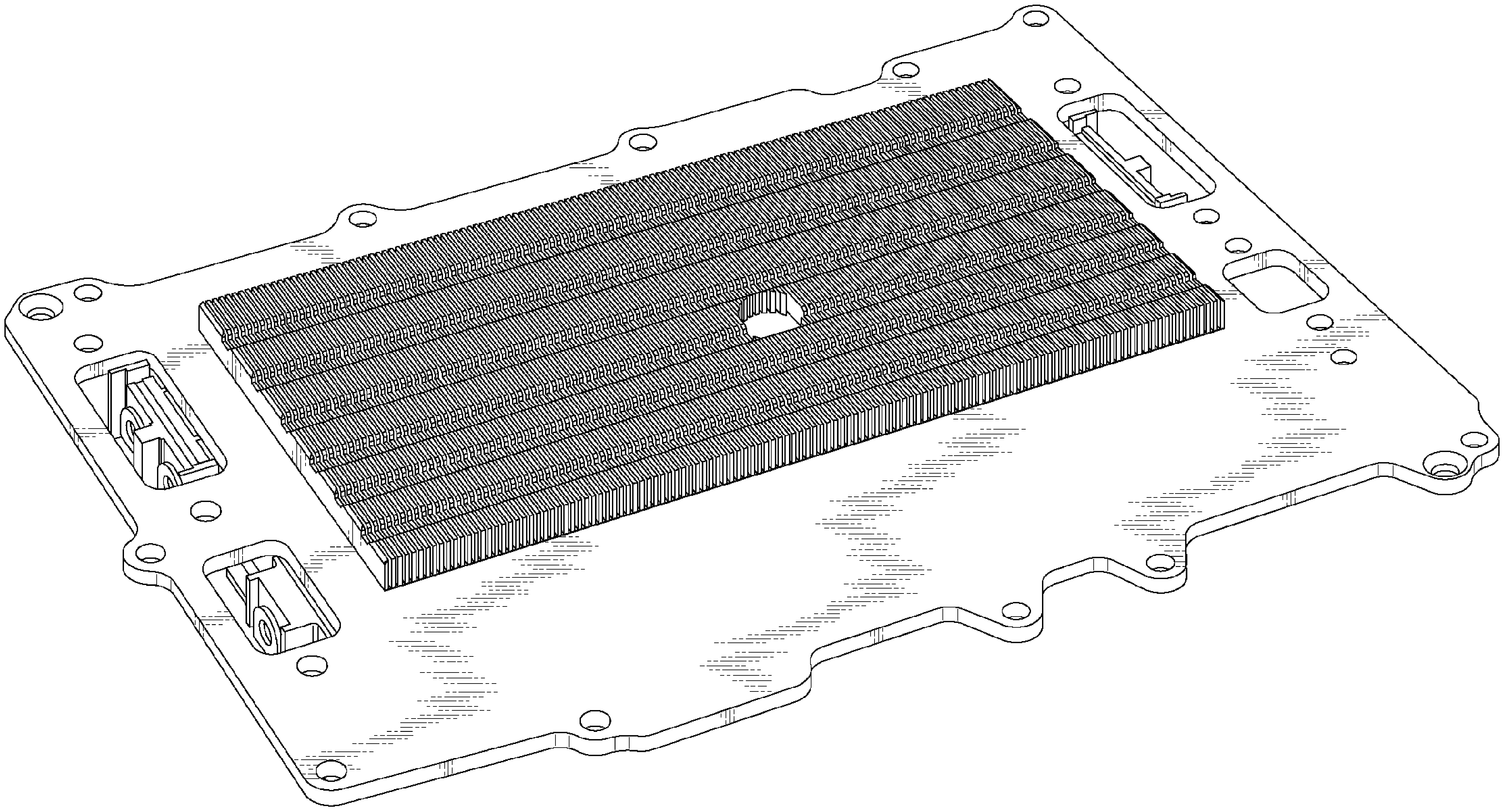

FIG.11